

Title (en)

DEVICE FOR DISSIPATING HEAT FROM ELECTRONIC COMPONENTS IN AN ELECTRONICS HOUSING

Title (de)

VORRICHTUNG ZUR WÄRMEABLEITUNG VON IN EINEM ELEKTRONIKGEHÄUSE ANGEORDNETEN ELEKTRONISCHEN BAUTEILEN

Title (fr)

DISPOSITIF DE DISSIPATION DE CHALEUR DE COMPOSANTS ÉLECTRONIQUES DANS UN BOÎTIER ÉLECTRONIQUE

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Application

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Abstract (en)

[origin: WO2023274767A1] The invention relates to a device for dissipating heat from electronic components in an electronics housing, in particular electronic components on a printed circuit board in an electronics housing. The invention for the first time provides a device which dissipates heat from electronic components in an electronics housing and is not exclusively based on primary heat dissipation via a thermal conduction paste. Instead, heat is dissipated via a working fluid that has cooling power in the electronics housing using evaporation and condensation.

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